



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-10-22
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
CLT03-1SC3	8CRC*U1P3AS1	A	9992	2020-10-22
	Amount	UoM	Unit type	ST ECOPACK Grade
	18	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	210	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	DM00553847	



Package Designator	Size	Nbr of instances	Shape	
Not Applicable	2.90,1.63,1.18	8	shape	
Comment	SOT 23 8L			

QueryList : RoHS Directive 2011/65/EU-July 2011 Annex II amended by Delegated Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_ March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.10	die - leadframe	5333

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Gold,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

Material Composition Declaration :						Mfr Item Name	8CRC*U1P3A51					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.558	mg	supplier	die	Silicon(Si)	7440-21-3		0.546	mg	978494	30332
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.006	mg	10753	333
				supplier	polymer coating	Polyimide	Proprietary		0.006	mg	10753	333
Leadframe	M-004 Copper and its alloys	9.672	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8		9.358	mg	967535	519889
				supplier	alloy & coating	Nickel(Ni)	7440-02-0		0.096	mg	9926	5333
				supplier	alloy & coating	Iron(Fe)	7439-89-6		0.203	mg	20988	11278
				supplier	alloy & coating	Phosphorus metal	7723-14-0		0.001	mg	103	56
				supplier	alloy & coating	Zinc(Zn)	7440-66-6		0.004	mg	414	222
				supplier	alloy & coating	Palladium(Pd)	7440-05-3		0.009	mg	931	500
				supplier	alloy & coating	Gold(Au)	7440-57-5		0.001	mg	103	56
Die attach	M-011 Other inorganic materials	0.125	mg	supplier	glue	Silver(Ag)	7440-22-4		0.103	mg	824000	5722
				supplier	glue	Rubber modified epoxy	proprietary		0.009	mg	72000	500
				supplier	glue	Ethoxyethoxy-ethyl acetate	112-15-2		0.010	mg	80000	556
				supplier	glue	BMI resin	proprietary		0.001	mg	8000	56
				supplier	glue	Carbonic ester	proprietary		0.001	mg	8000	56
				supplier	glue	Aromatic amine	proprietary		0.001	mg	8000	56
Bonding wires	M-008 Precious metals	0.062	mg	supplier	wire	Gold(Au)	7440-57-5		0.062	mg	1000000	3444
Encapsulation	M-011 Other inorganic materials	7.583	mg	supplier	mold compound	Silica vitreous	60676-86-0		6.521	mg	859950	362278
				supplier	mold compound	Epoxy type resin	proprietary		0.440	mg	58025	24444
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.379	mg	49980	21056
				supplier	mold compound	phenolic resin	proprietary		0.228	mg	30067	12667
				supplier	mold compound	Carbon black	1333-86-4		0.015	mg	1978	833